

1156886

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SMD socket, nominal current: 3 A, Test voltage: 500 V AC, number of positions: 10, pitch: 2.54 mm, color: black, contact surface: Gold, contact connection type: Socket, mounting: SMD soldering

Your advantages

- · Reliable mechanical and electrical connections thanks to the double-sided contact system
- · Designed for integration into the SMT soldering process
- · Clear and cost-optimized design
- · Suitable for a multitude of applications
- · Stacked, coplanar or orthogonal PCB connections enable maximum flexibility in the device

Commercial data

Item number	1156886
Packing unit	380 pc
Minimum order quantity	380 pc
Sales key	AA24
Product key	AAXABB
GTIN	4063151160333
Weight per piece (including packing)	1.61 g
Weight per piece (excluding packing)	1.6 g
Customs tariff number	85366930
Country of origin	CN



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Technical data

Notes

Notes on operation	The permissible voltage during operation depends on the application, taking into consideration the air clearances and
	creepage distances within the scope of insulation requirements in accordance with IEC 60664-1.

Product properties

Product type	SMD socket
Product family	FQ 2,54D/SV
Number of positions	10
Pitch	2.54 mm
Number of rows	2
Pin layout	Linear pad geometry

Electrical properties

Nominal current I _N	3 A (at 20°C 80-pos.)
Degree of pollution	3
Contact resistance	20 mΩ
Test voltage	500 V AC IEC 60512-4-1:2003

Dimensions

Dimensional drawing	h h
Pitch	2.54 mm
Width [w]	13.1 mm
Height [h]	11.2 mm
Length [I]	7.9 mm
Installed height	9.8 mm

Application

Contact cover	0.4 mm
Stack height	13.6 mm Tolerance: +1.3 mm (in combination with Range of articles:FQ 2,54D/PV)
Wipe length	1.3 mm
PCR design	

PCB desigr

Pad geometry	1.04 x 3.38 mm
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Material specifications

Material data - contact



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Dimension check

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Note	WEEE/RoHS-compliant, free of whiskers according to IEC 60068-2-82/JEDEC JESD 201
Contact material	Cu alloy
Surface characteristics	Selective coating
Metal surface contact area (top layer)	Gold (Au)
Metal surface contact area (middle layer)	Nickel (Ni)
Metal surface soldering area (top layer)	Tin (Sn)
Material data - housing	
Color (Housing)	black (9005)
Insulating material	PA
Insulating material group	T.
CTI according to IEC 60112	600
Flammability rating according to UL 94	V0
onnection 1	
Insulating material	PA
CTI according to IEC 60112	600
hermal test Test group C	IFC 60512-5-2:2002-02
Specification	IEC 60512-5-2:2002-02
Tested number of positions	80
nsulation resistance	
Specification	IEC 60512-3-1:2002-02
Insulation resistance, neighboring positions	> 1 GΩ
ir clearances and creepage distances	
Insulating material group	I
Minimum value for clearance and creepage distance	0.4 mm
chanical tests	
nsertion and withdrawal forces	
Result	Test passed
No. of cycles	100
Insertion strength per pos. approx.	2.9 N
Withdraw strength per pos. approx.	2.9 N
	2.9 N
Withdraw strength per pos. approx.	2.9 N IEC 60512-1-1:2002-02



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Packaging specifications

Type of packaging

pecification	IEC 60512-1-2:2002-02
Result	Test passed
ironmental and real-life conditions	
bration test	
Specification	IEC 60068-2-6:2007-12
Frequency	10 - 55 - 10 Hz
Sweep speed	1 octave/min
Amplitude	1.52 mm
Sweep speed	181 m/s²
Test duration per axis	2 h
urability test	
Specification	IEC 60512-9-1:2010-03 (following)
Contact resistance R ₁	20 mΩ
Contact resistance R ₂	30 mΩ
Insertion/withdrawal cycles	100
Insulation resistance, neighboring positions	> 1 GΩ
mbient conditions	
Ambient temperature (operation)	-40 °C 125 °C
Ambient temperature (storage/transport)	-40 °C 70 °C
Relative humidity (storage/transport)	30 % 70 %
Ambient temperature (assembly)	-5 °C 100 °C
	0 0
unting	
Mounting type	SMD soldering
Pin layout	Linear pad geometry
rocessing notes	
Process	Reflow soldering
Moisture Sensitive Level	MSL 1
Classification temperature T _c	260 °C

Tube magazine



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Classifications

UNSPSC 21.0

ECLASS

ECLASS-11.0	27460201
ECLASS-13.0	27460201
ECLASS-12.0	27460201
ETIM	
ETIM 9.0	EC002637
UNSPSC	

39121400



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Environmental product compliance

China RoHS	Environmentally friendly use period: unlimited = EFUP-e
	No hazardous substances above threshold values

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